

SEMATECH/SUNY SELECTS OKAMOTO GDM 300 SYSTEM FOR TSV PROCESS

Sematech / The Research Foundation of SUNY will utilize the GDM300 backgrinder for their TSV development.

June 11, 2009

Semiconductor consortium SEMATECH / The Research Foundation of SUNY (Albany, NY) will develop their Through Silicon Via (TSV) process using GDM300 Backgrinder. The System is a High-Precision wafer thinning tool.

After the grind process, stress release is achieved by dual high speed scanning polishing heads able to achieve +/- 5% non-uniformity. Improved die strength is achieved by simultaneously utilizing CMP and water polish. An integrated edge trimmer eliminates edge chipping and improves yield. Non-contact measurement devices enable precision thickness accuracy.

The GDM300 is able to process 8" or 12" wafers. The system is designed for thin wafer applications such as TSV, bonded wafers, SOI, and MEMS. Also available optionally in a full line system for single wafer thinning are dicing frame mounting, UV curing and detaping of protective tape. DAF tape can also be applied in lieu of standard dicing tape.



GDM 300 Full In-Line System

Okamoto Machine Tool Works, Ltd. - Japan:

www.okamoto.co.jp

Okamoto Corporation - CA & IL, USA :

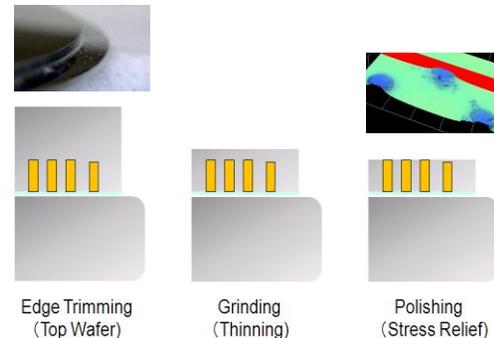
www.okamoto-sed.com

Okamoto Machine Tool Europe :

www.okamoto-europe.de

Okamoto Singapore :

www.os-okamoto.co.sg



Wafer Thinning Process